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- Single Chip With Easy Interface Between UART and Two Serial-Port Connectors of IBM™ PC/AT™ and Compatibles
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU Recommendation V.28
- Supports Data Rates up to 120 kbit/s
- Package Options Include Plastic Thin Shrink Small-Outline (DGG) and Shrink Small-Outline (DL) Packages

description

The SN752232 consists of dual ports, each containing three drivers and five receivers, which reduce board space and allow easy interconnection of the UART and two serial-port connectors of an IBM[™] PC/AT[™] and compatibles. The bipolar circuits and processing of this "dual GD75232" provide, a rugged, low-cost solution for this function.

The SN752232 complies with the requirements of the TIA/EIA-232-F and ITU V.28 standards. These standards are for data interchange between a host computer and a peripheral at signaling rates up to 20 kbit/s. The device supports data rates up to 120 kbit/s with lower capacitive loads (shorter cables). Interoperability at the higher signaling rates cannot be expected unless the designer has design control of the cable and the interface circuits at both ends. For interoperability at signaling rates up to 120 kbit/s, use of TIA/EIA-423-B (ITU V.10) and TIA/EIA-422-B (ITU V.11) standards is recommended.

The SN752232 is characterized for operation over the temperature range of 0°C to 70°C.

	(TOP VI	EW)	
V F	L U	10	
	1	48	
RIN1A	2	47	ROUT1A
RIN2A	3	46	ROUT2A
RIN3A	4	45	ROUT3A
DOUT1A	5	44	DIN1A
DOUT2A	6	43	DIN2A
RIN4A	7	42	ROUT4A
DOUT3A	8	41	DIN3A
RIN5A	9	40	ROUT5A
v _{ss} [10	39] GND
NC [11	38] NC
NC [12	37] NC
v _{dd} [13	36] v _{cc}
RIN1B	14	35	ROUT1B
RIN2B	15	34	ROUT2B
RIN3B [16	33	ROUT3B
DOUT1B	17	32	DIN1B
DOUT2B	18	31] DIN2B
RIN4B	19	30	ROUT4B
DOUT3B [20	29] DIN3B
RIN5B	21	28	ROUT5B
v _{ss} [22	27] GND
NC [23	26] NC
NC	24	25] NC

DGG OR DL PACKAGE

AVAILABLE OPTIONS

	PACKAGED DEVICES					
Τ _Α	PLASTIC SHRINK SMALL OUTLINE (DL)	PLASTIC THIN SHRINK SMALL OUTLINE (DGG)				
0°C to 70°C	SN752232DL	SN752232DGG				

The DL package also is available taped and reeled. Add the suffix R to the device type (e.g., SN752232DLR). The DGG package is only available taped and reeled.



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logic diagram (positive logic)



NOTE A: Numbers in parentheses are for B section.

schematic (each driver)



NOTE A: Resistor values shown are nominal.



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schematic (each receiver)



NOTE A: Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage (see Note 1): V _{CC}
V _{DD} 15 V
V _{SS} –15 V
Input voltage range, V _I : Driver
Receiver
Driver output voltage range, V _O –15 V to 15 V
Receiver low-level output current, I _{OL}
Package thermal impedance, θ _{JA} (see Note 2): DGG package
DL package
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds
Storage temperature range, T _{stg} –65°C to 150°C

⁺ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to network GND.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions

		MIN	NOM	MAX	UNIT	
VDD	Supply voltage	7.5	9	15	V	
VSS	Supply voltage	-7.5	-9	-15	V	
VCC	Supply voltage	4.5	5	5.5	V	
VIH	High-level input voltage (driver only)	1.9			V	
VIL	Low-level input voltage (driver only)			0.8	V	
1	High-level output current			-6	-6 mA	
ЮН	Receiver			-0.5	IIIA	
1	Driver			6	~ ^	
IOL	Low-level output current Receiver			16	mA	
Τ _Α	Operating free-air temperature	0		70	°C	

supply currents over recommended operating free-air temperature range

	PARAMETER		TEST CONDIT	IONS		MIN	MAX	UNIT
				V _{DD} = 9 V,	$V_{SS} = -9 V$		30	
		All inputs at 1.9 V,	No load	V _{DD} = 12 V,	$V_{SS} = -12 V$		38	
I_{DD} Supply current from V_D	Supply current from Voo			V _{DD} = 15 V,	$V_{SS} = -15 V$		50	mA
				V _{DD} = 9 V,	$V_{SS} = -9 V$		9	ША
		All inputs at 0.8 V,	No load	V _{DD} = 12 V,	$V_{SS} = -12 V$		11	
				V _{DD} = 15 V,	$V_{SS} = -15 V$		18	
				V _{DD} = 9 V,	$V_{SS} = -9 V$		-30	
		All inputs at 1.9 V,	No load	V _{DD} = 12 V,	$V_{SS} = -12 V$		-38	
100	Supply ourrest from Vac			V _{DD} = 15 V,	V _{SS} = -15 V		-50	mA
ISS	Supply current from V_{SS}			V _{DD} = 9 V,	$V_{SS} = -9 V$		-6.4	ША
		All inputs at 0.8 V, No load $V_{DD} = 12 V$, $V_{SS} = -12 V$	$V_{SS} = -12 V$		-6.4			
				V _{DD} = 15 V,	V _{SS} = -15 V		-6.4	
ICC	Supply current from V_{CC}	V _{CC} = 5 V,	All inputs at 5 V,	No load			60	mA

DRIVER SECTION

electrical characteristics over recommended operating free-air temperature range, V_{DD} = 9 V, V_{SS} = -9 V, V_{CC} = 5 V (unless otherwise noted)

	PARAMETER		TEST CONDITIC	NS	MIN	TYP	MAX	UNIT
VOH	High-level output voltage	V _{IL} = 0.8 V,	$R_L = 3 k\Omega$,	See Figure 1	6	7.5		V
VOL	Low-level output voltage (see Note 3)	V _{IH} = 1.9 V,	$R_L = 3 k\Omega$,	See Figure 1		-7.5	-6	V
lн	High-level input current	V _I = 5 V,	See Figure 2				10	μA
۱ _{۱L}	Low-level input current	$V_{I} = 0,$	See Figure 2				-1.6	mA
IOS(H)	High-level short-circuit output current (see Note 4)	V _{IL} = 0.8 V,	V _O = 0,	See Figure 1	-4.5	-12	-19.5	mA
IOS(L)	Low-level short-circuit output current	V _{IH} = 2 V,	$V_{O} = 0,$	See Figure 1	4.5	12	19.5	mA
rO	Output resistance (see Note 5)	$V_{CC} = V_{DD} = V_{CC}$	/ _{SS} = 0,	$V_{O} = -2 V \text{ to } 2 V$	300			Ω

NOTES: 3. The algebraic convention, where the more positive (less negative) limit is designated as maximum, is used in this data sheet for logic levels only (e.g., if –10 V is maximum, the typical value is a more negative voltage).

4. Output short-circuit conditions must maintain the total power dissipation below absolute maximum ratings.

5. Test conditions are those specified by TIA/EIA-232-F and as listed above.



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switching characteristics, V_{CC} = 5 V, V_{DD} = 12 V, V_{SS} = -12 V, T_A = 25°C (see Figure 3)

	PARAMETER	TEST	CONDITIONS		MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	R_L = 3 kΩ to 7 kΩ,	C _L = 15 pF			315	500	ns
^t PHL	Propagation delay time, high- to low-level output	$R_L = 3 k\Omega$ to 7 k Ω ,	C _L = 15 pF			75	175	ns
+	Transition time, low, to high lovel output	$\mathbf{P}_{\mathbf{k}} = 2 \mathbf{k} 0$ to $7 \mathbf{k} 0$	C _L = 15 pF			60	100	ns
^t TLH	Transition time, low- to high-level output	$R_{L} = 3 k\Omega \text{ to } 7 k\Omega$	C _L = 2500 pF,	See Note 6		1.7	2.5	μs
+	Transition time, high- to low-level output	$P_{\rm L} = 2 k\Omega to 7 k\Omega$	CL = 15 pF			40	75	ns
^t THL	Transition time, high- to low-level output	$R_{L} = 3 R_{22} 10 7 R_{22}$	C _L = 2500 pF,	See Note 6		1.5	2.5	μs

NOTE 6: Measured between ±3-V and ±3-V points of the output waveform (TIA/EIA-232-F conditions), all unused inputs are tied either high or low.

RECEIVER SECTION

electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST C	TEST CONDITIONS		TYP [†]	MAX	UNIT	
\/. _	Desitive asing input threshold voltage	$T_A = 25^{\circ}C$	See Figure 5	1.75	1.9	2.3	V	
VIT+	Positive-going input threshold voltage	$T_A = 0^{\circ}C$ to 70 $^{\circ}C$	See Figure 5	1.55		2.3	v	
V_{IT-}	Negative-going input threshold voltage			0.75	0.97	1.25	V	
V _{hys}	Input hysteresis voltage (V _{IT+} – V _{IT} –)			0.5			V	
Varia		1au 0.5 mA	V _{IH} = 0.75 V	2.6	4	5	V	
VOH	High-level output voltage	I _{OH} = -0.5 mA	Inputs open	2.6				
VOL	Low-level input voltage	I _{OL} = 10 mA,	V _I = 3 V		0.2	0.45	V	
	High-level input current	V _I = 25 V,	See Figure 5	3.6		8.8	mA	
ΙН	High-level liput current	V _I = 3 V,	See Figure 5	0.43			ША	
1	Low-level output current	V _I = -25 V,	See Figure 5	-3.6		-8.8	mA	
ΊĽ		$V_{I} = -3 V,$	See Figure 5	-0.43	3		ША	
los	Short-circuit output current	See Figure 4			-3.4	-12	mA	

[†] All typical values are at $T_A = 25^{\circ}C$, $V_{CC} = 5$ V, $V_{DD} = 9$ V, and $V_{SS} = -9$ V.

switching characteristics, V_{CC} = 5 V, V_{DD} = 12 V, V_{SS} = –12 V, T_A = 25°C (see Figure 6)

	PARAMETER	TEST C	ONDITIONS	MIN	TYP	MAX	UNIT				
^t PLH	Propagation delay time, low- to high-level output				107	250	ns				
^t PHL	Propagation delay time, high- to low-level output	С _L = 50 рF,	$R_1 = 5 k\Omega$		42	150	ns				
^t TLH	Transition time, low- to high-level output		CL = 50 pr,	$C_{L} = 50 \text{ pr},$	$C_{L} = 50 \text{ pr},$	С[= 50 рг,	KL = 0 K22		175	350	ns
^t THL	Transition time, high- to low-level output				16	60	ns				
^t PLH	Propagation delay time, low- to high-level output				100	160	ns				
^t PHL	Propagation delay time, high- to low-level output	С _L = 15 рF,	C _L = 15 pF,	C: 15 pF		C1 - 15 pE	$P_{\rm L} = 1.5 \rm kO$		60	100	ns
^t TLH	Transition time, low- to high-level output			RL = 1.5 kΩ		90	175	ns			
^t THL	Transition time, high- to low-level output				15	50	ns				



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PARAMETER MEASUREMENT INFORMATION







Figure 2. Driver Test Circuit for IIH and IIL





Figure 3. Driver Test Circuit and Voltage Waveforms



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PARAMETER MEASUREMENT INFORMATION



Figure 4. Receiver Test Circuit for IOS



Figure 5. Receiver Test Circuit for V_{IT} , V_{OH} , and V_{OL}





Figure 6. Receiver Propagation and Transition Times



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TYPICAL CHARACTERISTICS

DRIVER SECTION





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TYPICAL CHARACTERISTICS



Figure 13



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APPLICATION INFORMATION

Diodes placed in series with the V_{DD} and V_{SS} leads protect the SN752232 in the fault condition in which the device outputs are shorted to ±15 V, and the power supplies are at low and provide low-impedance paths to ground (see Figure 15).



Figure 15. Power-Supply Protection to Meet Power-Off Fault Conditions of TIA/EIA-232-F



NOTE A: Numbers in parentheses are for B section.

Figure 16. Typical Connection Per Port



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